HLMP-3707, HLMP-3907, HLMP-3750, HLMP-3850, HLMP-3950, HLMP-3960, HLMP-3390, HLMP-3490, HLMP-3590, HLMP-1340, HLMP-1440, HLMP-1540, HLMP-K640

AVAGO

T-13/4 (5 mm), T-1 (3 mm), Ultra-Bright LED Lamps

Data Sheet



Description

These non-diffused lamps out-perform conventional LED lamps. By utilizing new higher intensity material, we achieve superior product performance.

The HLMP-3750/-3390/-1340 Series Lamps are Gallium Arsenide Phosphide on Gallium Phosphide red light emitting diodes. The HLMP-3850/-3490/-1440 Series are Gallium Arsenide Phosphide on Gallium Phosphide yellow light emitting diodes. The HLMP-3950/3590/3960/1540/ K640 Series Lamps are Gallium Phosphide green light emitting diodes.

Features

- Improved brightness
- Improved color performance
- Available in popular T-1 and T-1³/₄ packages
- New sturdy leads
- IC compatible/low current capability
- Reliable and rugged
- Choice of 3 bright colors
 - High Efficiency Red
 - High Brightness Yellow
 - High Performance Green

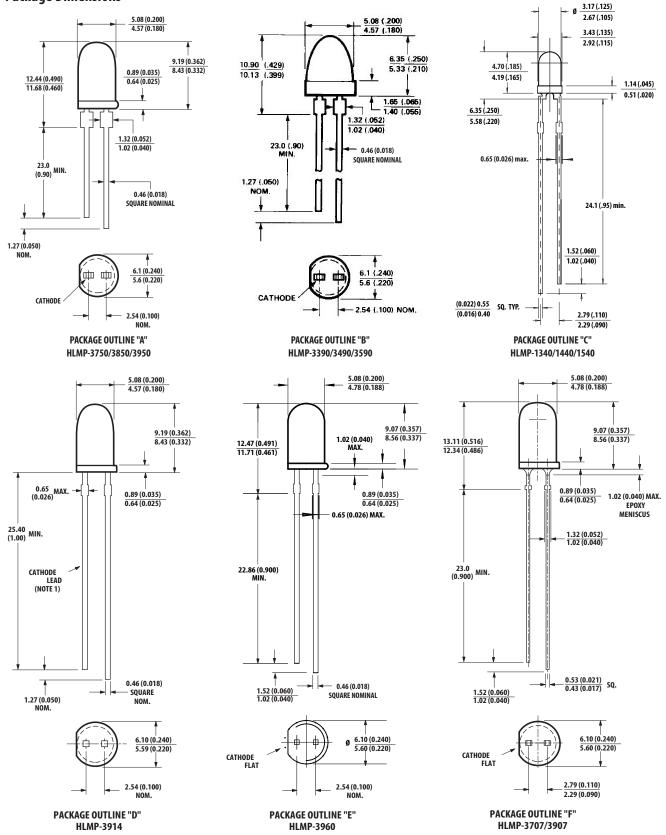
Applications

- · Lighted switches
- Backlighting front panels
- Light pipe sources
- Keyboard indicators

Selection Guide

		Luminous Intensity Iv (mcd) @ 20mA					
Package Description	Color	Device HLMP-	Min.	Тур.	Max.	2 _q 1/2 Degree	Package Outline
T-1 ³ / ₄	Red	3707-L00xx	90.2	-	-	24	F
		3750	90.2	125.0	-	24	А
		3750-L00xx	90.2	125.0	-	24	А
	Yellow	3850	96.2	140.0	-	24	А
		3850-K00xx	96.2	140.0	-	24	А
		3850-KL0xx	96.2	150.0	294.0	24	А
	Green	3907-K00xx	111.7	-	-	24	F
		3914-K00xx	111.7	-	-	24	D
		3950	111.7	265.0	-	24	А
		3950-K00xx	111.7	265.0	-	24	А
		3950-LM0xx	170.0	300.0	490.0	24	А
		3960-K0xxx	111.7	265.0	-	24	Е
T-1 ³ / ₄ Low Profile	Red	3390	35.2	55.0	-	32	В
	Yellow	3490	37.6	55.0	-	32	В
	Green	3590	43.6	55.0	-	32	В
T-1	Red	1340	35.2	55.0	-	45	С
		1340-H00xx	13.8	-	-	45	С
		1340-J00xx	35.2	55.0	-	45	С
	Yellow	1440	23.5	45.0	-	45	С
		1440-H00xx	23.5	45.0	-	45	С
	Green	1540	27.3	45.0	-	45	С
		1540-H00xx	27.3	45.0	-	45	С
		1540-IJ0xx	43.6	60.0	139.6	45	С
	Emerald Green	K640	4.2	21.0	-	45	С
		K640-FGNxx	10.6	20.0	34.0	45	С

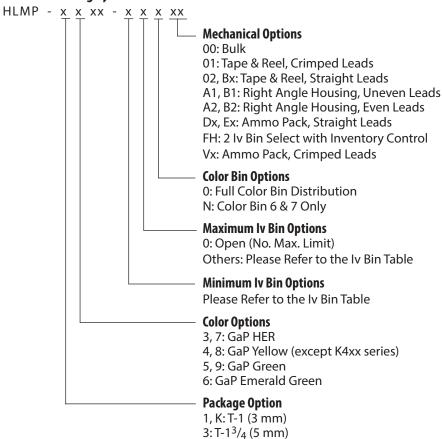
Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. An epoxy meniscus may extend about 1 mm (0.40") down the leads.
- 3. For PCB hole recommendations, see the Precautions section.





Absolute Maximum Ratings at $T_A = 25^{\circ}C$

Parameter	Red	Yellow	Green/Emerald Green	Units
Peak Forward Current	90	60	90	mA
Average Forward Current ^[1]	25	20	25	mA
DC Current ^[2]	30	20	30	mA
Transient Forward Current ^[3] (10 µs Pulse)	500	500	500	mA
Reverse Voltage ($I_R = 100 \mu A$)	5	5	5	V
LED Junction Temperature	110	110	110	°C
Operating Temperature Range	-40 to +100	-40 to +100	-20 to +100	°C
Storage Temperature Range	-40 to +100	-40 to +100	-40 to +100	°C

Notes

- 1. See Figure 2 to establish pulsed operating conditions.
- 2. For Red and Green series derate linearly from 50°C at 0.5 mA/°C. For Yellow series derate linearly from 50°C at 0.2 mA/°C.
- 3. The transient peak current is the maximum non-recurring peak current the devices can withstand without damaging the LED die and wire bonds. It is not recommended that the device be operated at peak currents beyond the Absolute Maximum Peak Forward Current.

Electrical/Optical Characteristics at $T_A = 25^{\circ}C$

Symbol	Description	T-1 ³ / ₄	T-1 ³ / ₄ Low Dome	T-1	Min.	Тур.	Max.	Units	Test Conditions
λ _{PEAK} Peak	Peak	37xx	3390	1340		635		nm	Measurement
	Wavelength	38xx	3490	1440		583			at Peak
		39xx	3590	1540		565			
				K640		558			
λ_d	Dominant	37xx	3390	1340		626		nm	Note 1
	Wavelength	38xx	3490	1440		585			
		39xx	3590	1540		569			
				K640		560			
$\Delta\lambda^3/_4$	Spectral Line	37xx	3390	1340		40		nm	
	Halfwidth	38xx	3490	1440		36			
		39xx	3590	1540		28			
				K640		24			
τ_{S}	Speed of	37xx	3390	1340		90		ns	
	Respond	38xx	3490	1440		90			
		39xx	3590	1540		500			
				K640		3100			
C	Capacitance	37xx	3390	1340		11		pF	$V_F = 0$,
	•	38xx	3490	1440		15		•	f = 1 MHz
		39xx	3590	1540		18			
				K640		35			
Rθ _{J-PIN}	Thermal	37xx	3390			210		°C/W	Junction to
	Resistance	38xx	3490			210			Cathode Lead
		39xx	3590			210			
						510			
				1340		290			
				1440		290			
				1540		290			
				K640		290			
V_{F}	Forward	37xx	3390	1340	1.5	1.9	2.6	V	$I_F = 20 \text{ mA}$
	Voltage	38xx	3490	1440	1.5	2.1	2.6		(Figure 3)
		39xx	3590	1540	1.5	2.2	3.0		
				K640		2.2	3.0		
V_R	Reverse	37xx	3390	1340	5.0			V	$I_F = 100 \mu A$
	Breakdown	38xx	3490	1440					
	Voltage	39xx	3590	1540					
				K640					
η_{v}	Luminous	37xx	3390	1340		145		<u>lumens</u>	Note 2
	Efficacy	38xx	3490	1440		500		watt	
	•	39xx	3590	1540		595			
				K640		655			

Notes:

^{1.} The dominant wavelength, λd , is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.

^{2.} The radiant intensity, le, in watts per steradian, may be found from the equation le = IV/η_V , where IV is the luminous intensity in candelas and η_V is the luminous efficacy in lumens/watt.

Red, Yellow, and Green

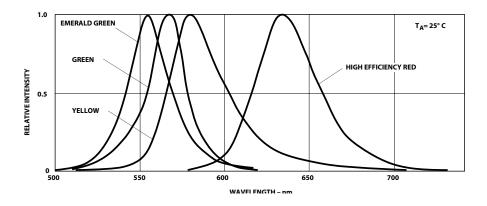


Figure 1. Relative intensity vs. wavelength.

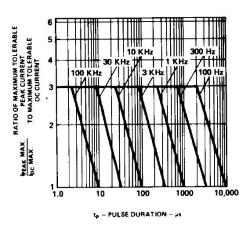


Figure 2. Maximum tolerable peak current vs. pulse duration. (I_{DC} MAX as per MAX ratings).

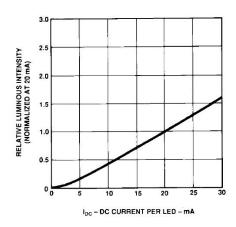


Figure 4. Relative luminous intensity vs. forward current.

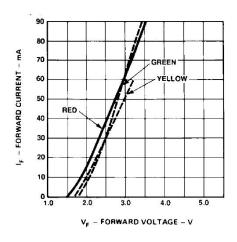


Figure 3. Forward current vs. forward voltage.

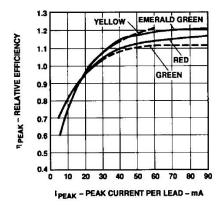


Figure 5. Relative efficiency (luminous intensity per unit current) vs. peak current.

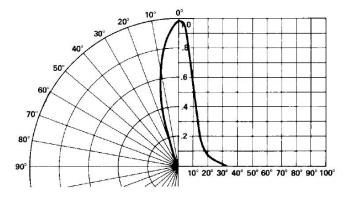


Figure 6. Relative luminous intensity vs. angular displacement. T-1 3 /4 lamp.

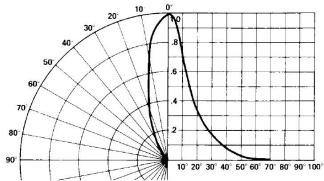


Figure 7. Relative luminous intensity vs. angular displacement. T-1 3 /4 low profile lamp.

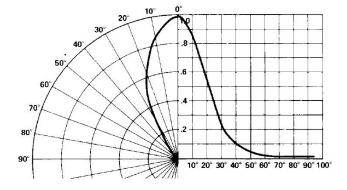


Figure 8. Relative luminous intensity vs. angular displacement. T-1 lamp.

Intensity Bin Limits

	Dill Lilling	Intensity Ra	nge (mcd)	
Color	Bin	Min.	Max.	
Red	G	9.7	15.5	
	Н	15.5	24.8	
	1	24.8	39.6	
	J	39.6	63.4	
	K	63.4	101.5	
	L	101.5	162.4	
	М	162.4	234.6	
	N	234.6	340.0	
	0	340.0	540.0	
F	Р	540.0	850.0	
	Q	850.0	1200.0	
	R	1200.0	1700.0	
	S	1700.0	2400.0	
	Т	2400.0	3400.0	
	U	3400.0	4900.0	
	V	4900.0	7100.0	
	W	7100.0	10200.0	
	X	10200.0	14800.0	
	Υ	14800.0	21400.0	
	Z	21400.0	30900.0	

Maximum tolerance for each bin limit is $\pm 18\%$.

Intensity Bin Limits (continued)

		Intensity Rang	nsity Range (mcd)	
Color	Bin	Min.	Max.	
Yellow	F	10.3	16.6	
	G	16.6	26.5	
	Н	26.5	42.3	
	1	42.3	67.7	
	J	67.7	108.2	
	K	108.2	173.2	
	L	173.2	250.0	
	M	250.0	360.0	
	N	360.0	510.0	
	0	510.0	800.0	
	P	800.0	1250.0	
	Q	1250.0	1800.0	
	R	1800.0	2900.0	
	S	2900.0	4700.0	
	T	4700.0	7200.0	
	U	7200.0	11700.0	
	V	11700.0	18000.0	
	W	18000.0	27000.0	
Green/	А	1.1	1.8	
Emerald	В	1.8	2.9	
Green	С	2.9	4.7	
	D	4.7	7.6	
	E	7.6	12.0	
	F	12.0	19.1	
	G	19.1	30.7	
	Н	30.7	49.1	
	1	49.1	78.5	
	J	78.5	125.7	
	K	125.7	201.1	
	L	201.1	289.0	
	M	289.0	417.0	
	N	417.0	680.0	
	0	680.0	1100.0	
	P	1100.0	1800.0	
	Q	1800.0	2700.0	
	R	2700.0	4300.0	
	S	4300.0	6800.0	
	Т	6800.0	10800.0	
	U	10800.0	16000.0	
	V	16000.0	25000.0	
	W	25000.0	40000.0	

Color Categories

	Lambda (nm))
Cat #	Min.	Max.
9	552.5	555.5
8	555.5	558.5
7	558.5	561.5
6	561.5	564.5
6	561.5	564.5
5	564.5	567.5
4	567.5	570.5
3	570.5	573.5
2	573.5	576.5
1	582.0	584.5
3	584.5	587.0
2	587.0	589.5
4	589.5	592.0
5	592.0	593.0
1	597.0	599.5
2	599.5	602.0
3	602.0	604.5
4	604.5	607.5
5	607.5	610.5
6	610.5	613.5
7	613.5	616.5
8	616.5	619.5
	9 8 7 6 5 4 3 2 1 3 2 4 5 1 2 3 4 5 6 7	Cat # Min. 9 552.5 8 555.5 7 558.5 6 561.5 5 564.5 4 567.5 3 570.5 2 573.5 1 582.0 3 584.5 2 587.0 4 589.5 5 592.0 1 597.0 2 599.5 3 602.0 4 604.5 5 607.5 6 610.5 7 613.5

Maximum tolerance for each bin limit is $\pm 0.5 \text{ nm}$.

Maximum tolerance for each bin limit is $\pm 18\%$.

Mechanical Option Matrix

Mechanical Option Code	Definition
00	Bulk Packaging, minimum increment 500 pcs/bag
01	Tape & Reel, crimped leads, min. increment 1300 pcs/bag for T-1 ³ / ₄ , 1800 pcs/bag for T-1
02	Tape & Reel, straight leads, min. increment 1300 pcs/bag for T-1 ³ / ₄ , 1800 pcs/bag for T-1
A1	T-1, Right Angle Housing, uneven leads, minimum increment 500 pcs/bag
A2	T-1, Right Angle Housing, even leads, minimum increment 500 psc/bag
B1	T-1 ³ / ₄ , Right Angle Housing, uneven leads, minimum increment 500 pcs/bag
B2	T-1 ³ / ₄ , Right Angle Housing, even leads, minimum increment 500 psc/bag
BJ	T-1, Tape & Reel, straight leads, minimum increment 2000 pcs/bag
EG	Ammo Pack, straight leads in 5 K increment
FH	Devices that require inventory control and 2 I _v bin select
VR	Ammo Pack, crimped leads, min. increment 2 k for T-1 $^3/_4$ and T-1

Note:

All categories are established for classification of products. Products may not be available in all categories. Please contact your local Avago representative for further clarification/information.

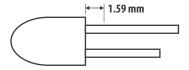
Precautions:

Lead Forming:

- The leads of an LED lamp may be preformed or cut to length prior to insertion and soldering on PC board.
- For better control, it is recommended to use proper tool to precisely form and cut the leads to applicable length rather than doing it manually.
- If manual lead cutting is necessary, cut the leads after the soldering process. The solder connection forms a mechanical ground which prevents mechanical stress due to lead cutting from traveling into LED package. This is highly recommended for hand solder operation, as the excess lead length also acts as small heat sink.

Soldering and Handling:

- Care must be taken during PCB assembly and soldering process to prevent damage to the LED component.
- LED component may be effectively hand soldered to PCB. However, it is only recommended under unavoidable circumstances such as rework. The closest manual soldering distance of the soldering heat source (soldering iron's tip) to the body is 1.59mm. Soldering the LED using soldering iron tip closer than 1.59mm might damage the LED.



- ESD precaution must be properly applied on the soldering station and by personnel to prevent ESD damage to the LED component that is ESD sensitive. For details, refer to Avago application note AN 1142. The soldering iron used should have a grounded tip to ensure electrostatic charge is properly grounded.
- Recommended soldering conditions:

	Wave Soldering ^{[1],[2]}	Manual Solder Dipping
Pre-heat Temperature	105°C Max.	-
Pre-heat Time	60 sec Max.	_
Peak Temperature	250°C Max.	260°C Max.
Dwell Time	3 sec Max.	5 sec Max.

Notes:

- 1. These conditions refer to measurement with a thermocouple mounted at the bottom of PCB.
- To reduce thermal stress experienced by the LED, it is recommended that you use only the bottom preheaters.

 Wave soldering parameters must be set and maintained according to the recommended temperature and dwell time. Customer is advised to perform daily check on the soldering profile to ensure that it is always conforming to recommended soldering conditions.

Note:

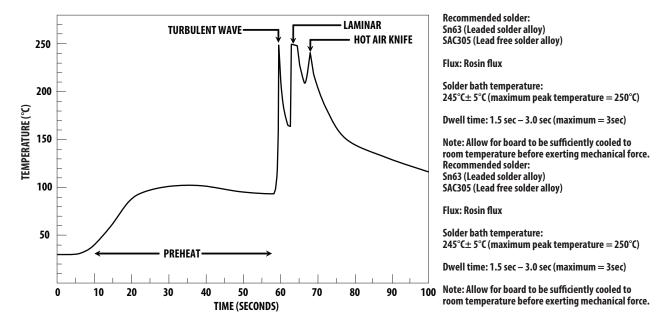
- PCB with different size and design (component density) will have different heat mass (heat capacity). This might cause a change in temperature experienced by the board if same wave soldering setting is used. So, it is recommended to re-calibrate the soldering profile again before loading a new type of PCB.
- Customer is advised to take extra precaution during wave soldering to ensure that the maximum wave temperature does not exceed 250°C and the solder contact time does not exceeding 3sec. Over-stressing the LED during soldering process might cause premature failure to the LED due to delamination.
- Any alignment fixture that is being applied during wave soldering should be loosely fitted and should not apply weight or force on LED. Non metal material is recommended as it will absorb less heat during wave soldering process.
- At elevated temperature, LED is more susceptible to mechanical stress. Therefore, PCB must allowed to cool down to room temperature prior to handling, which includes removal of alignment fixture or pallet.
- If PCB board contains both through hole (TH) LED and other surface mount components, it is recommended that surface mount components be soldered on the top side of the PCB. If surface mount need to be on the bottom side, these components should be soldered using reflow soldering prior to insertion the TH LED.
- Recommended PC board plated through holes (PTH) size for LED component leads:

	LED Component Lead Size	Diagonal	Plated Through- Hole Diameter	
Lead size (typ.)	0.45 × 0.45 mm	0.636 mm	0.98 to 1.08 mm	
	(0.018 × 0.018 in.)	(0.025 in)	(0.039 to 0.043 ir	
Dambar shear-	0.65 mm	0.919 mm	_	
off area (max.)	(0.026 in)	(0.036 in)		
Lead size (typ.)	0.50 × 0.50 mm	0.707 mm	1.05 to 1.15 mm	
	(0.020 × 0.020 in.)	(0.028 in)	(0.041 to 0.045 in)	
Dambar shear-	0.70 mm	0.99 mm	_	
off area (max.)	(0.028 in)	(0.039 in)		

 Over-sizing the PTH can lead to a twisted LED after it is clinched. On the other hand, undersizing the PTH can make inserting the TH LED difficult.

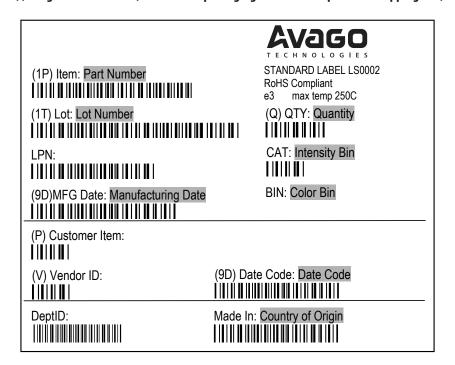
For more information about soldering and handling of TH LED lamps, refer to application note AN5334.

Example of Wave Soldering Temperature Profile for TH LED



Packaging Label:

(i) Avago Mother Label: (Available on packaging box of ammo pack and shipping box)



(ii) Avago Baby Label (Only available on bulk packaging)

AVAGO TECHNOLOGIES Lamps Baby Label	RoHS Compliant e3 max temp 250C
(1P) PART #: Part Number	
(1T) LOT #: Lot Number	
(9D)MFG DATE: Manufacturing Date	QUANTITY: Packing Quantity
C/O: Country of Origin	
Customer P/N:	CAT: Intensity Bin
Supplier Code:	BIN: Color Bin
	DATECODE:

For product information and a complete list of distributors, please go to our web site: **www.avagotech.com**

